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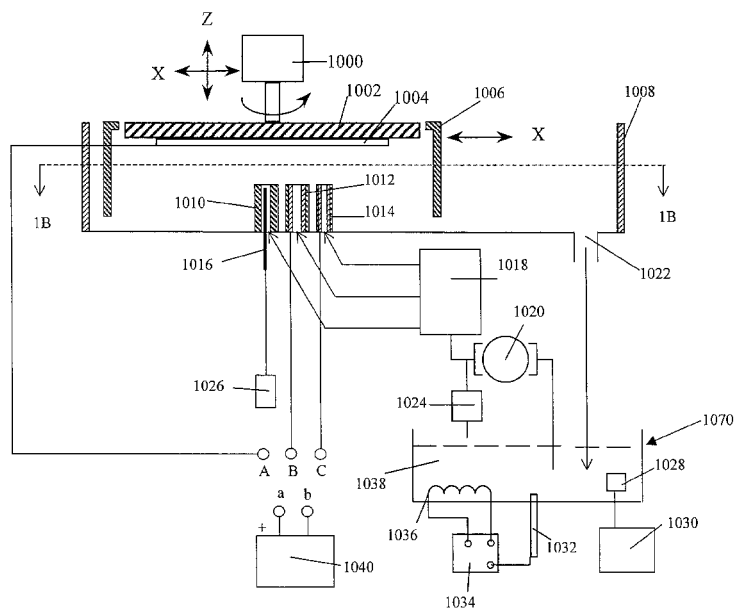
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(54) Title: ELECTROPOLISHING ASSEMBLY AND METHODS FOR ELECTROPOLISHING CONDUCTIVE LAYERS



(57) Abstract: In one aspect of the present invention, an exemplary apparatus and method are provided for electropolishing a conductive film on a wafer (1004). An apparatus includes a wafer chuck (1002) for holding a wafer, an actuator (1000) for rotating the wafer chuck, and a nozzle (1010) configured to electropolish the wafer. The apparatus may further include a conductive ring or a shroud (1006). A method of electropolishing a conductive film on a wafer includes rotating a wafer chuck with sufficient speed such that electrolyte fluid incident upon the wafer flows on the surface of the wafer towards the edge of the wafer.



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